



SLP4N65S/SLF4N65S

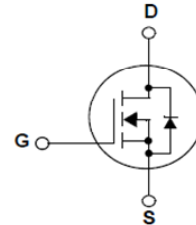
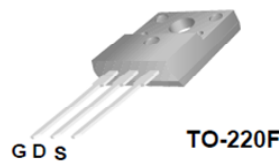
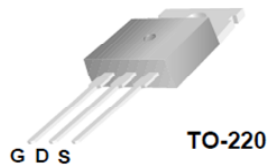
SLP4N65S/SLF4N65S 650V N-Channel MOSFET

General Description

This Power MOSFET is produced using Maple semi's advanced planar stripe DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switched mode power supplies, active power factor correction based on half bridge topology.

Features

- 4.0A, 650V, $R_{DS(on)} = 2.5\Omega @ V_{GS} = 10V$
- Low gate charge (typical 13.3nC)
- High ruggedness
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



Absolute Maximum Ratings $T_C = 25^\circ C$ unless otherwise noted

Symbol	Parameter	SLP4N65S	SLF4N65S	Units
V_{DSS}	Drain-Source Voltage	650		V
I_D	Drain Current	- Continuous ($T_C = 25^\circ C$)	4.0	A
		- Continuous ($T_C = 100^\circ C$)	2.4	A
I_{DM}	Drain Current - Pulsed (Note 1)	16		A
V_{GSS}	Gate-Source Voltage	± 30		V
EAS	Single Pulsed Avalanche Energy (Note 2)	128		mJ
I_{AR}	Avalanche Current (Note 1)	4.5		A
E_{AR}	Repetitive Avalanche Energy (Note 1)	3.5		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	5.5		V/ns
P_D	Power Dissipation ($T_C = 25^\circ C$)	104	36	W
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150		$^\circ C$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300		$^\circ C$

Thermal Characteristics

Symbol	Parameter	Max.		Units
		SLP4N65S	SLF4N65S	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.20	3.47	$^\circ C/W$
$R_{\theta JS}$	Thermal Resistance, Case-to-Sink Typ.	0.5	--	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	$^\circ C/W$

Electrical CharacteristicsT_C = 25° C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	650	--	--	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C	--	0.6	--	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 650 V, V _{GS} = 0 V	--	--	25	μA
		V _{DS} = 520 V, T _C = 125°C	--	--	250	μA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V	--	--	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V	--	--	-100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	2.0	--	4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 2.0 A	--	2.0	2.5	Ω
g _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 2.0 A (Note 4)	--	2.5	--	S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz	--	590	--	pF
C _{oss}	Output Capacitance		--	48	--	pF
C _{rss}	Reverse Transfer Capacitance		--	5	--	pF
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} = 300 V, I _D = 4.0 A, R _G = 25 Ω (Note 4, 5)	--	23	--	ns
t _r	Turn-On Rise Time		--	33	--	ns
t _{d(off)}	Turn-Off Delay Time		--	61	--	ns
t _f	Turn-Off Fall Time		--	200	--	ns
Q _g	Total Gate Charge		V _{DS} = 480 V, I _D = 4.0A, V _{GS} = 10 V (Note 4, 5)	--	13.3	--
Q _{gs}	Gate-Source Charge	--		3.0	--	nC
Q _{gd}	Gate-Drain Charge	--		4.8	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain-Source Diode Forward Current		--	--	4.0	A
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	16	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 4.0 A	--	--	1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 4.0 A,	--	390	--	ns
Q _{rr}	Reverse Recovery Charge	di _F / dt = 100 A/us (Note 4)	--	1.5	--	μC

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. I_{AS} = 4.0A, L=15mH, V_{DD} = 50V, R_G = 25Ω, Starting T_J = 25° C
3. I_{SD} ≤ 4.0A, di/dt ≤ 200A/us, V_{DD} ≤ BV_{DSS}, Starting T_J = 25° C
4. Pulse Test : Pulse width ≤ 300us, Duty cycle ≤ 2%
5. Essentially independent of operating temperature

Typical Characteristics

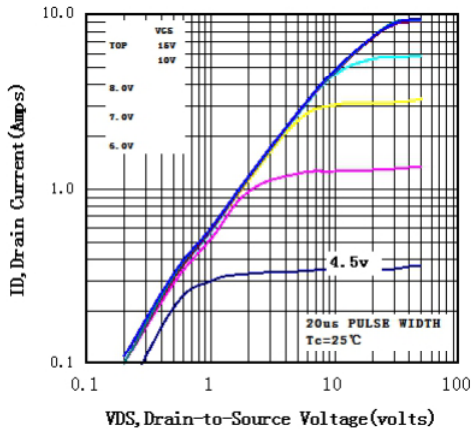


Figure 1. Typical Output Characteristics
Tc=25°C

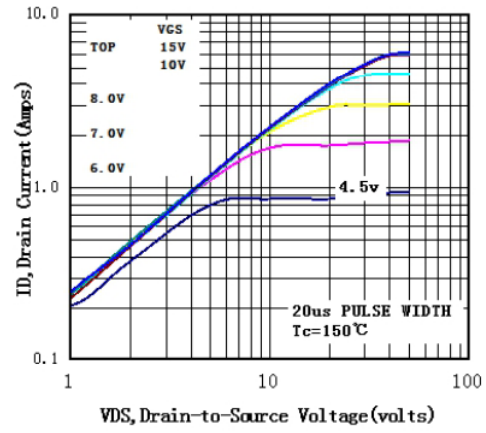


Figure 2. Typical Output Characteristics
Tc=150°C

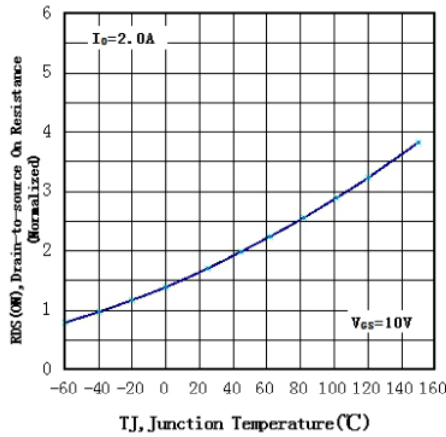


Figure 3. Normalized Resistance VS
Temperature

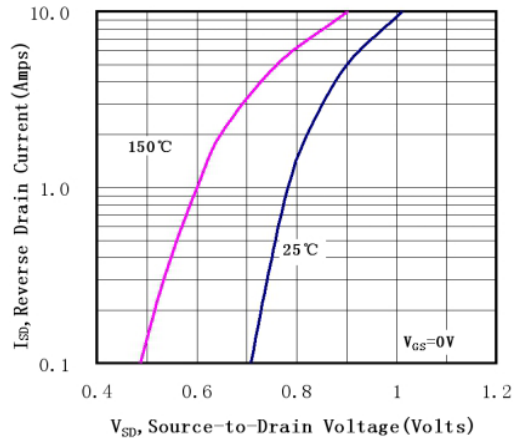


Figure 4. Typical Source-Drain Diode
Forward Voltage

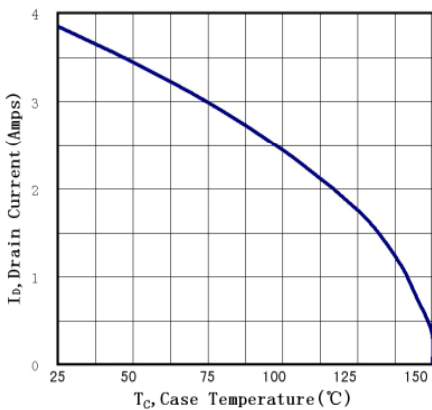


Figure 5. Maximum Current VS
Case Temperature

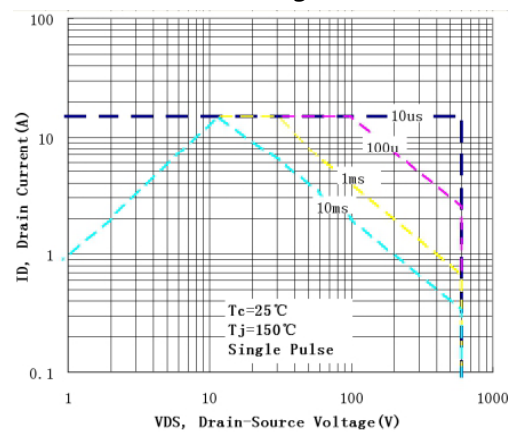


Figure 6-1. Maximum Safe Operating Area
TO-220F

Typical Characteristics (Continued)

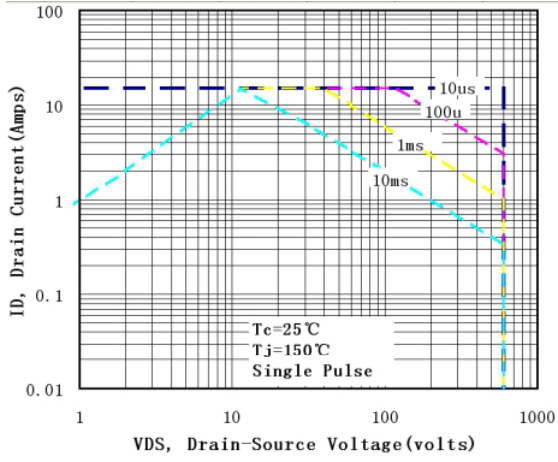
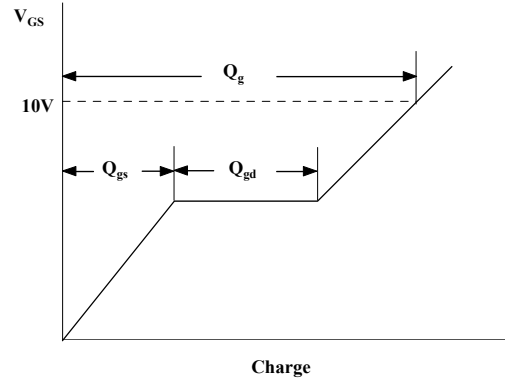
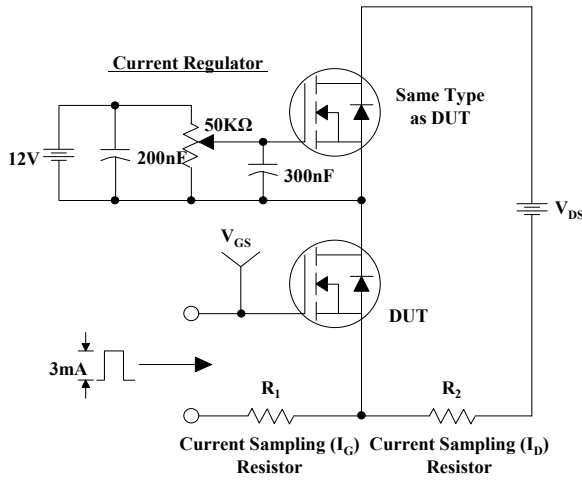
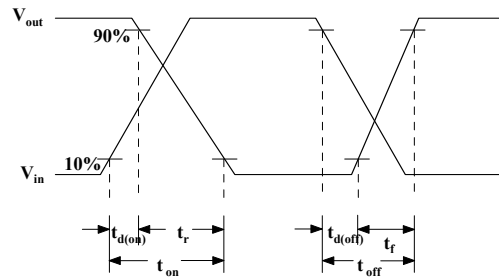
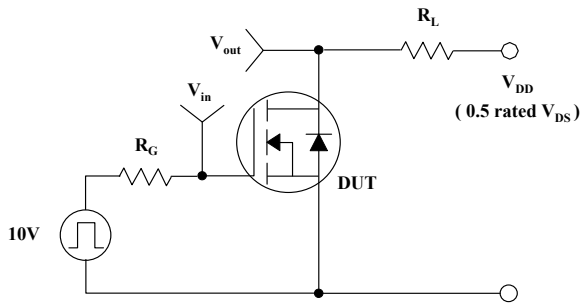


Figure 6-2. Maximum Safe Operating Area TO-220

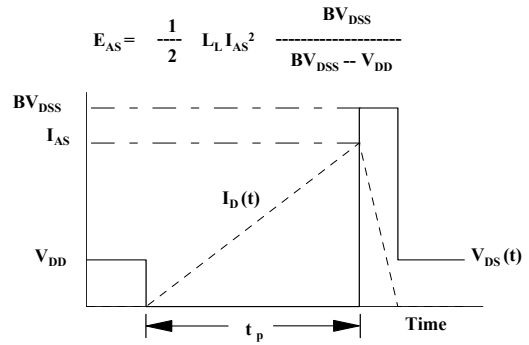
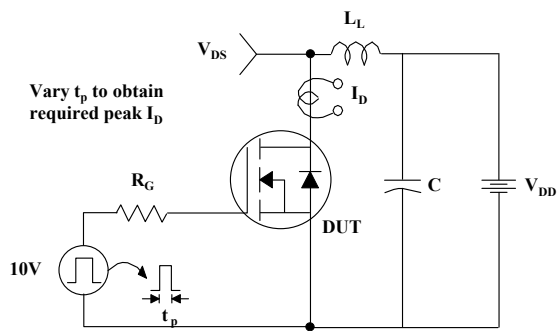
Gate Charge Test Circuit & Waveform



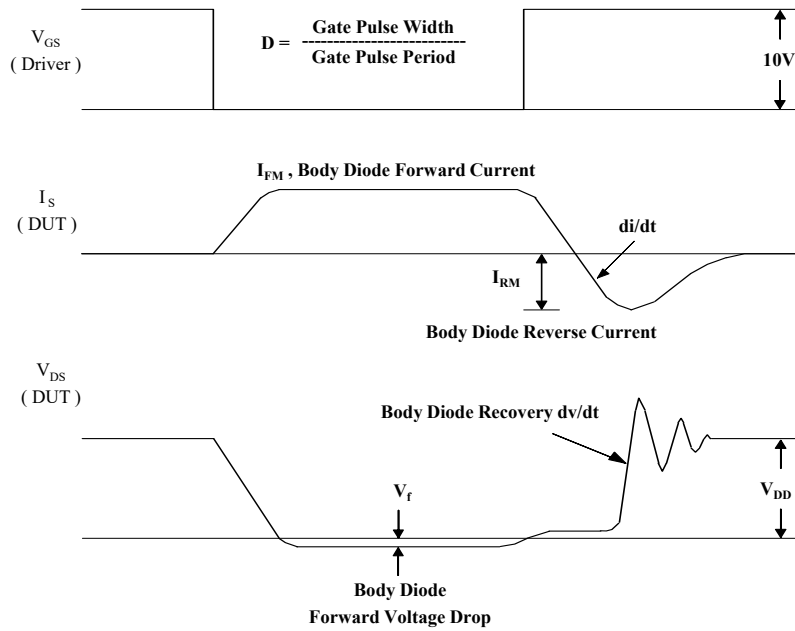
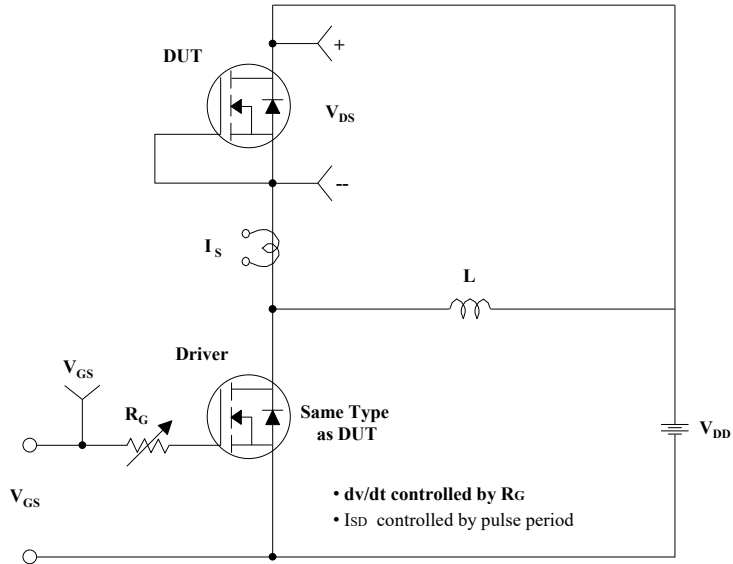
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms



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